

Examiner-Initiated Interview Summary	Application No.	Applicant(s)	
	10/796,655	HORIKOSHI, HIROSHI	

All Participants:

(1) Thanhha Pham.

Status of Application: _____

(3) _____.

(2) Christopher Rausch.

(4) _____.

Date of Interview: 13 September 2006

Time: _____

Type of Interview:

- Telephonic
- Video Conference
- Personal (Copy given to: Applicant Applicant's representative)

Exhibit Shown or Demonstrated: Yes No

If Yes, provide a brief description: _____.

Part I.

Rejection(s) discussed:

Claims discussed:

1-20

Prior art documents discussed:

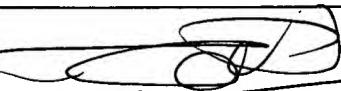
Part II.

SUBSTANCE OF INTERVIEW DESCRIBING THE GENERAL NATURE OF WHAT WAS DISCUSSED:

Discuss claimed languages to overcome 112 2nd paragraph rejection issue (see attachment)

Part III.

- It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview directly resulted in the allowance of the application. The examiner will provide a written summary of the substance of the interview in the Notice of Allowability.
- It is not necessary for applicant to provide a separate record of the substance of the interview, since the interview did not result in resolution of all issues. A brief summary by the examiner appears in Part II above.



(Examiner/SPE Signature)

(Applicant/Applicant's Representative Signature – if appropriate)

Interview summary
dated 9/13/06

In claim 1,

Line 2, delete "the"

Line 8, change "a second wiring" to - second wirings -

Line 8, change "it is" to - they are -

Line 8, after "wherein" insert - one of --

Line 9, change "wiring" (1st occurrence) to - wirings -

Line 9, change "the memory element" to - the magnetoresistance effect type memory element -

Line 10, change "the memory element" to - the magnetoresistance effect type memory element -

Line 10, after "comprises" delete "the"

Line 12, change "a side portion" to - side portions -

Line 12, change "the second wiring" to - the second wirings -

Line 13, change "wiring" to - wirings -

Line 15, change "the second wiring," to - each of the second wirings, -

In claim 4,

Line 3, change "portion" to - portions -

Line 3, change "wiring" to - wirings -

Line 6, change "portion" to - portions -

Line 6, change "wiring" to - wirings -

Line 7, change "wiring" to - wirings -

In claim 5,

Line 3, change "said second wiring is" to - said second wirings are -

Line 3, change "a trench formed on" to - trenches formed in -

Line 3, change "a barrier layer" to - barrier layers -

Line 5, change "said barrier layer" to - said barrier layers -

Line 5, change "the side portion of the second wiring is" to - the side portions of the second wirings are -

In claim 6,

Line 3, change "said second wiring is formed in a trench formed on" to -- said second wirings are formed in trenches in -

Line 3, change "a barrier layer" to - barrier layers -

Line 4, change "the step" to - a step -

Line 7, change "the surface of the second wiring" to - the side surface and the top surface of each of the second wirings -

Line 10, change "the second wiring" to - each of the second wirings -

In claim 7,

Line 3, change "said second wiring is formed in a trench formed on" to -- said second wirings are formed in trenches in -

Line 3, change "a barrier layer" to - barrier layers -

Line 5, change "the steps of" to - steps of -

Line 8, change "the surface of the second wiring" to - the side surface and the top surface of each of the second wirings -

Line 9, delete "the"

Line 11, change "the second wiring" to - each of the second wirings -

Cancel claims 8-20